



Automatic Surface Grinder DAG810

Automatic grinding for research and production

Single-axis automatic grinder

The DAG810 is a compact, automatic grinder for workpieces up to 8" in diameter. It has one spindle and one chuck table and is designed to process a variety of materials.

Small footprint – 1.02 m²

Machine dimensions: 600 (W) x 1,700 (D) x 1,780 (H) mm

Precision grinding

The newly developed high-rigidity, low-vibration spindle achieves superior grinding results and is capable of in-feed grinding and creep feed grinding (user-specified specification).

Unlimited materials

Process hard or brittle substrates of various diameters with ease. The DAG810 is also the choice for processing a wide variety of electronic components.



Easy operation

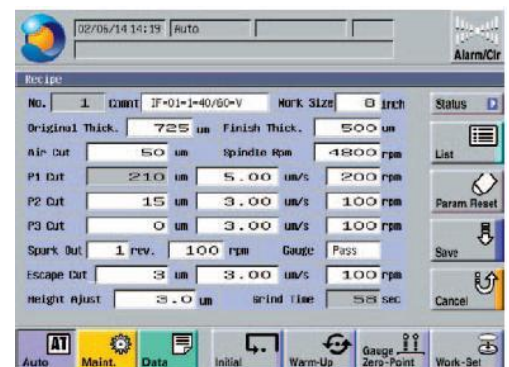
The LCD touch screen graphical user interface makes operation both intuitive and easy.

Special options for a variety of needs

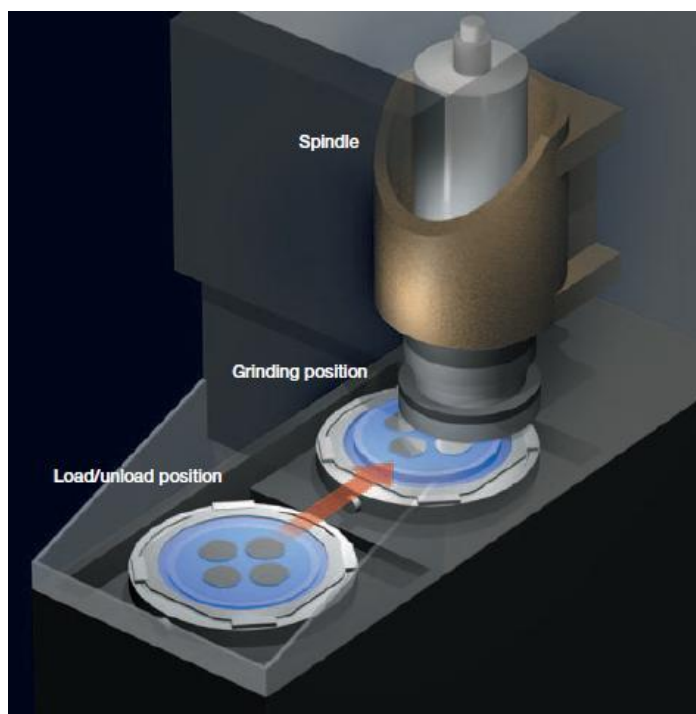
- Can be equipped with either one or two probe-height gauges (option)
- In-feed grinding for workpieces up to ø300 mm (option)
- 8" frame grinding (option)
- Creep-feed grinding for workpieces up to ø200 mm in diameter (user-specified specification)

High-precision applications

- Processes silicon and compound semiconductors for analysis.
- Grinds resin for CSP and WL-CSP
- Performs copper-post exposure and other metal applications
- Improves the planarity of lithium tantalate and lithium niobate
- Processes green ceramics and sapphire (small diameter)



LCD touch screen



*A special jig is required for ring frame grinding

Specifications

Specification		Unit	
Wafer Diameter		mm	φ 200 (φ 4"/5"/6"/8" with universal chuck table use)
Grinding Method		-	Anomalous In-feed grinding with wafer rotation
Grinding Wheels		mm	Φ200 Diamond Wheel
Spindle	Output	kW	4.2
	Rated torque	N·m	5.9
	Revolution speed range	min ⁻¹	1,000 - 7,000
Grinding Accuracy	Thickness variation within one workpiece	μm	Less than 1.5 (with dedicated chuck table)
	Finished surface roughness	μm	Ry 0.13 (with #2000 finish) Ry 0.15 (with #1400 finish)
Machine dimensions(W×D×H)		mm	600 × 1,700 × 1,780
Machine weight		kg	Approx. 1,300

Environmental conditions

- Use clean, oil-free air at a dew point of -15 °C or less. (Use a residual oil: 0.1 ppm. Filtration rating: 0.01 μm/99.5 % or more).
- Keep room temperature fluctuations within ±1 °C of the set value. (Set value should be between 20 - 25 °C).
- Keep grinding water + 0 - 2 °C above room temperature (fluctuations within 1 °C over one hour).
- Keep spindle cooling water temperature between 20 - 25 °C (fluctuations within 2 °C over an hour).
- The machines should be used in an environment, free from external vibration. Do not install machine near a ventilation opening, heat generation equipment or oil mist generating parts.
- This machine uses water. In case of water leakage, please install the machine on the floor with sufficient waterproofing and drainage treatments.
- * All the pressures are described using gauge pressure.
- * The above specifications may change due to technical modifications. Please confirm when placing your order.
- * For further information please contact your local sales representatives.
- * When you use it anything other than the deionized water, please contact your local representatives.